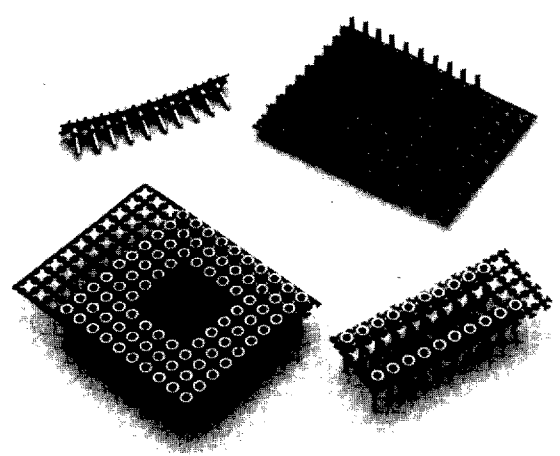


9.3



"Pull-Off" Carrier Socket Strips

Garry's single and dual socket strips are supplied with your choice of Kapton® or Politrix® carriers along with your choice of terminals. Once soldered to the board the "Pull-off" carrier is discarded leaving free stand alone terminals. Both carriers will withstand wave, vapor phase and infrared soldering applications.

- Stand alone pins allow for maximizing heat dissipation.
- Low Profile.
- Excellent solder joint inspection and cleaning.
- Maximum space utilization.

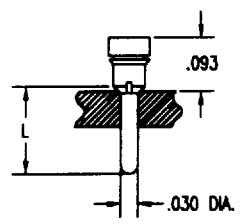
Materials:

Carriers:
 Kapton® is a registered trademark of DuPont.
 Politrix® is a registered trademark of Eastman Kodak.

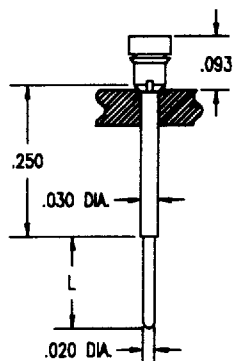
Spring contact:
 Beryllium copper, Gold over nickel plating.

Outer sleeve:
 Brass, Gold over nickel, or
 Tin Lead over nickel plating.

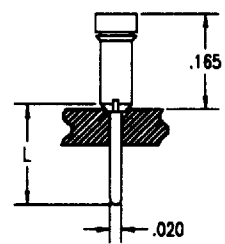
Plating options and specifications are available by contacting either the Garry factory or your local representative.



LP,LF



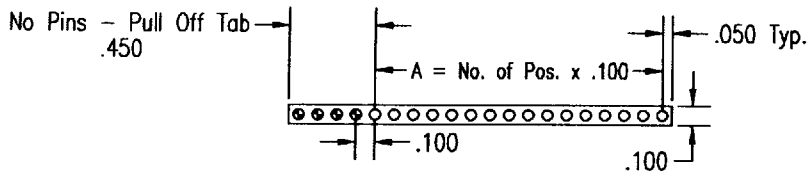
PE



LW



Single In-Line (S.I.L.) Pull-Off



XXX-XX - XX - X

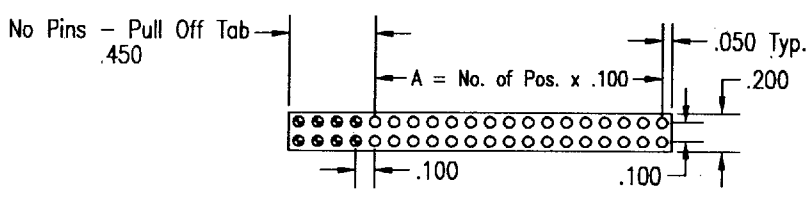
SERIES-PIN COUNT		
	#OF PINS	Material
2007-02 Thru 2007-40	2 Thru 40	Politrix [⊗]
2008-01 Thru 2008-40	2 Thru 40	Kapton [⊗]

PIN STYLE		
	DESCRIPTION	L DIM.(in.)
LW	Solder Tail	.128
LP	Solder Tail	.135
PE	Solder Tail	.160
LF	Solder Tail	.165

PLATING			
	CONTACT	SLEEVE	THICKNESS(u)
B	Gold	Gold	30/10
D	Gold	Tin	30/200

9.4

Dual In-Line (D.I.L.) Pull-Off



XXX-XX - XX - X

SERIES-PIN COUNT		
	#OF PINS	Material
2207-04 Thru 2207-80 (2X40 POS.)	4 Thru 80	Politrix [⊗]
2208-04 Thru 2208-80 (2X40 POS.)	4 Thru 80	Kapton [⊗]

PIN STYLE		
	DESCRIPTION	L DIM.(in.)
LW	Solder Tail	.128
LP	Solder Tail	.135
PE	Solder Tail	.160
LF	Solder Tail	.165

PLATING			
	CONTACT	SLEEVE	THICKNESS(u)
B	Gold	Gold	30/10
D	Gold	Tin	30/200

Specifications

Material Specifications for Screw Machine Products

Insulators

High temperature vapor phase and infrared compatible

Ryton (PPS)

Continuous use temp.	220°C
Heat deflection temp.(@ 264 PSI)	260°C
UL rating	94V-0

FR-4 Glass Epoxy

Continuous use temp.	140°C
Heat deflection temp.(@ 264 PSI)	149°C
UL rating	94V-0

Standard temperature wave solder compatible

Thermoplastic Polyester (PBT)

Continuous use temp.	140°C
Heat deflection temp.(@ 264 PSI)	204°C

Kapton

Temperature rating	-269°C to +400°C
Thickness	.005/.007
U/L94 VO rated	

Politrex

Temperature rating	-60°C to +150°C
Thickness	.005/.007
U/L94 VO rated	

Outer Body/Terminal

Brass - Alloy 360 Q hard per QQ-B-626

Contact Clips

Beryllium Copper (Be Cu) #25 hard heat treated

Plating Specifications

Plating Code "B"

Contact: 30 micro inches of gold per MIL-G-45204 over 50 micro inches min. of nickel per QQ-N-290

Outer Body: 10 micro inches of gold per MIL-G-204 type II over 50 micro inches min. of nickel per QQ-N-290

Plating Code "D"

Contact: 30 micro inches of gold per MIL-G-45204 type II over 50 micro inches min. of nickel per QQ-N-290

Outer Body: 200 micro inches min. of 90/10 tin lead per MIL-P-81728 type 1 over 50 micro inches min. of nickel per QQ-N-290

*Other Plating Requirements consult factory

Garry offers three (3) types of inter contact clips.

- *Standard insertion clip - 4 finger (used on SIP/DIP products)*
- *Low insertion clip - 6 finger (used on PGA STD Pin counts)*
- *Ultra low insertion clip - 3 finger (used on high pin count PGA and Interstitial PGA)*

Insertion/withdrawal specification using a .018 dia. polished steel pin

	<i>INS</i>	<i>withdrawal</i>
STD 4 finger clip	8 oz max	3 oz min
Low insertion clip	2 oz max	0.5 oz min
Ultra low insertion clip	1 oz max	0.3 oz min

16.1

Typical performance characteristics for Screw Machine Products

- *Contact Resistance (MIL-STD-202 E method 302)*
10 MIL/ohms max percontact
- *Contact Rating (for 10 C temperature rise)*
3 Amps
- *Capacitance (MIL-STD-202E method 302)*
0.2 PF
- *Insulation Resistance (MIL-STD-1344 method 3003.1)*
10,000 Megaohms(min)
- *Dielectric Withstanding Voltage(DWV) (MIL-STD-1344 method 3001.1)*
1000 VAC(RMS)
- *Vibration (MIL-STD-1344 method 2005.1 condition III)*
- *Shock (MIL-STD-1344 method 2004.1 condition G)*
- *Solderability (MIL-STD-202 method 208)*

